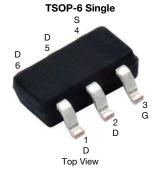
Si3129DV

www.vishay.com

Vishay Siliconix



Marking Code: BU

PRODUCT SUMMARY					
V _{DS} (V)	-80				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -10 V	0.0827				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -4.5 V	0.1242				
Q _g typ. (nC)	5.6				
I _D (A) ^a	-5.4				
Configuration	Single				

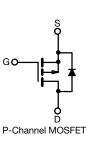
FEATURES

P-Channel 80 V (D-S) MOSFET

- TrenchFET® power MOSFET
- 100 % R_g tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Power management for portable and consumer
 - Load switches
 - DC/DC converters



RoHS

COMPLIANT

HALOGEN

FREE

ORD	DERING	INFOR	MATION	
		INFUR		

Package	TSOP-6 Single
Lead (Pb)-free and halogen-free	Si3129DV-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	-80	
Gate-source voltage		V _{GS}	±20	V
	T _C = 25 °C		-5.4	
	T _C = 70 °C		-4.4	
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	-3.8 ^{b, c}	
	T _A = 70 °C		-3.0 ^{b, c}	
Pulsed drain current (t = 300 µs)	·	I _{DM}	-20	А
Continuous source-drain diode current	T _C = 25 °C		-3.5	
	T _A = 25 °C	I _S	-1.7 ^{b, c}	
		I _{AS}	15	
Single pulse avalanche energy	L = 0.1 mH	E _{AS}	11	
	T _C = 25 °C		4.2	
Maximum power dissipation	T _C = 70 °C		2.7	14/
	T _A = 25 °C	P _D	2 ^{b, c}	W
	T _A = 70 °C		1.3 ^{b, c}	
Operating junction and storage temperature ra	T _J , T _{stq}	-55 to 150	°C	

THERMAL RESISTANCE RATINGS							
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT		
Maximum Junction-to-Ambient b, d	t ≤ 5 s	R _{thJA}	45	62.5	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	25	30	0/10		

Notes

a. T_C = 25 °C

b. Surface mounted on 1" x 1" FR4 board

c. t = 5 s

d. Maximum under steady state conditions is 110 °C/W

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Si3129DV

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = -250 \mu\text{A}$	-80	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_J$	I _D = -10 mA	-	-115	-		
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	4.8	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$	-1.5	-	-2.5	V	
Gate-source leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V	-	-	± 100	nA	
Zere gete voltage drein ourrent		V_{DS} = -80 V, V_{GS} = 0 V	-	-	-10		
Zero gate voltage drain current	IDSS	V_{DS} = -80 V, V_{GS} = 0 V, T_{J} = 55 °C	-	-	-50	μA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \leq$ -5 V, V_{GS} = -10 V	-5	-	-	А	
Drain-source on-state resistance ^a	Р	V_{GS} = -10 V, I _D = -3.8 A	-	0.0689	0.0827		
Drain-source on-state resistance ~	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -3.1 \text{ A}$	-	0.0994	0.1242	Ω	
Dynamic ^b							
Input capacitance	Ciss		-	805	-	pF	
Output capacitance	Coss	V_{DS} = -40 V, V_{GS} = 0 V, f = 1 MHz	-	265	-		
Reverse transfer capacitance	C _{rss}		-	10	-		
Total acto charge	0	V_{DS} = -40 V, V_{GS} = -10 V, I_{D} = -3.8 A	-	12	18	nC	
Total gate charge	Qg		-	5.6	8.4		
Gate-source charge	Q _{gs}	V_{DS} = -40 V, V_{GS} = -4.5 V, I_D = -3.8 A	-	3.1	-		
Gate-drain charge	Q _{gd}		-	1.4	-		
Gate resistance	Rg	f = 1 MHz	0.8	4.4	8.8	Ω	
Turn-on delay time	t _{d(on)}		-	15	30		
Rise time	tr	V_{DD} = -40 V, R_{L} = 13.3 Ω	-	8	16		
Turn-off delay time	t _{d(off)}	$I_D\cong$ -3 A, V_{GEN} = - 10 V, R_g = 1 Ω	-	25	50		
Fall time	t _f		-	12	24		
Turn-on delay time	t _{d(on)}		-	28	56	ns	
Rise time	tr	V_{DD} = -40 V, R_L = 13.3 Ω	-	42	84		
Turn-off delay time	t _{d(off)}	$\text{I}_\text{D}\cong$ -3 A, V_GEN = - 4.5, R_g = 1 Ω	-	24	48		
Fall time	t _f		-	15	30		
Drain-Source Body Diode Characterist	tics						
Continuous source-drain diode current	ls	T _C = 25 °C	-	3.5		^	
Pulse diode forward current	I _{SM}		-	-	-20	A	
Body diode voltage	V _{SD}	$I_{\rm S} = -3$ A, $V_{\rm GS} = 0$ V	-	-0.8	-1.2	V	
Body diode reverse recovery time	t _{rr}		-	38	57	ns	
Body diode reverse recovery charge	Q _{rr}		-	50	75	nC	
Reverse recovery fall time	ta	l _F = -3 A, dl/dt = 100 A/μs, T _J = 25 °C	-	26	-		
Reverse recovery rise time	t _b		-	12	-	ns	

Notes

a. Pulse test; pulse width $\leq 300~\mu\text{s},~\text{duty}~\text{cycle} \leq 2~\%$

b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2

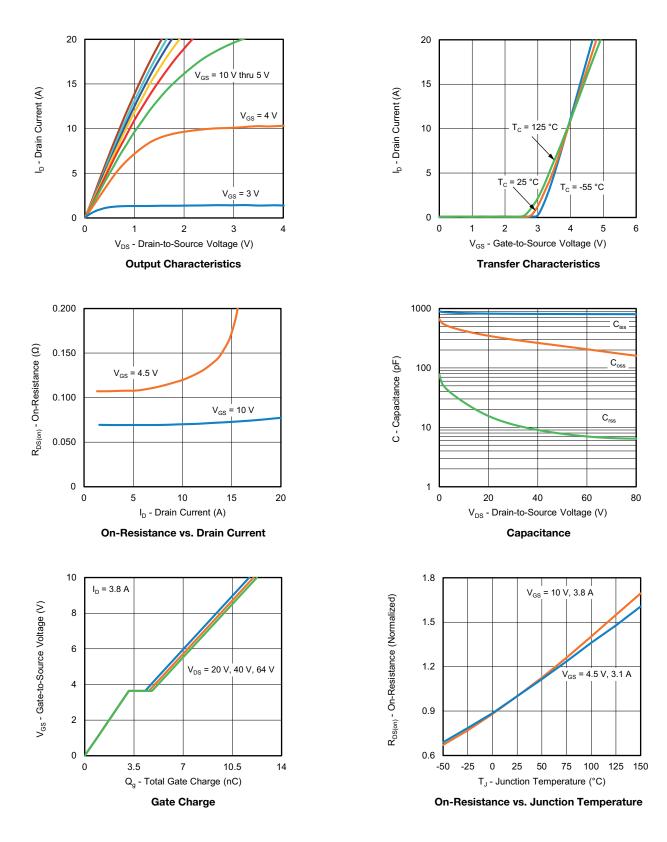
Document Number: 78984

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Vishay Siliconix

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



S20-0813-Rev. A, 19-Oct-2020

3

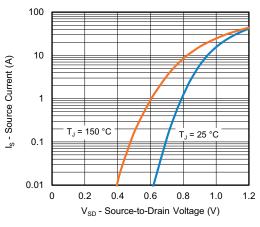
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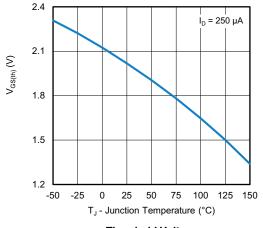
Si3129DV

Vishay Siliconix

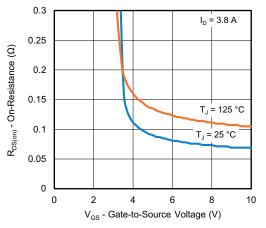
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



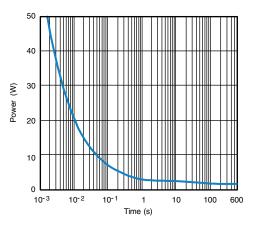
Source-Drain Diode Forward Voltage



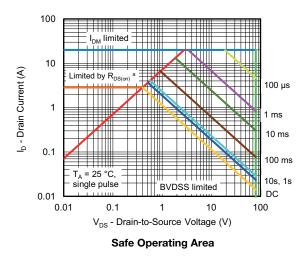




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

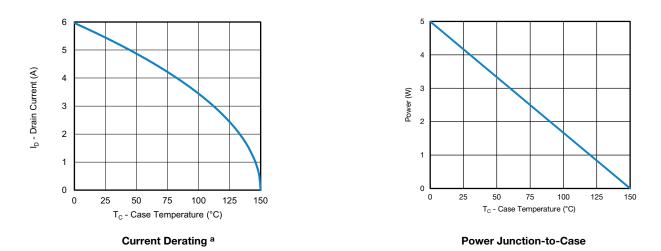
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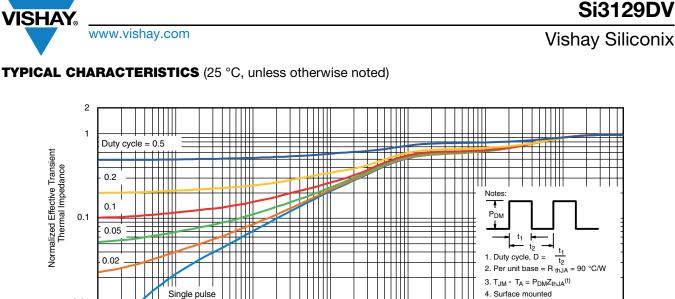
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



0.01 10-4

10⁻³

10-2

Normalized Thermal Transient Impedance, Junction-to-Ambient

Square Wave Pulse Duration (s)

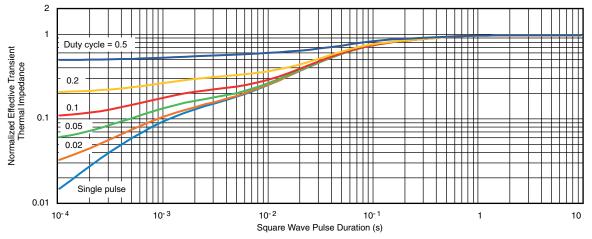
1

10

100

600

10-1



Normalized Thermal Transient Impedance, Junction-to-Foot

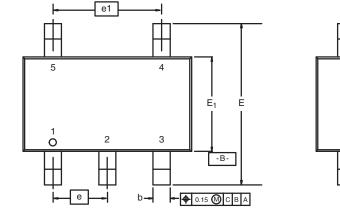
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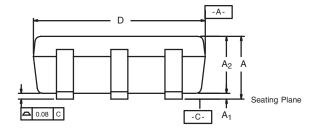
Package Information

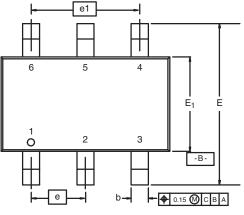
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TSOP: 5/6-LEAD JEDEC Part Number: MO-193C

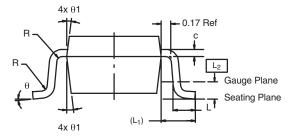


5-LEAD TSOP





6-LEAD TSOP



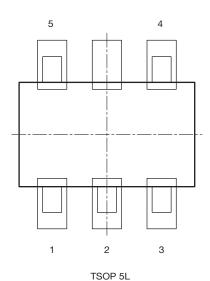
	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A ₁	0.01	-	0.10	0.0004	-	0.004	
A ₂	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
Е	2.70	2.85	2.98	0.106	0.112	0.117	
E ₁	1.55	1.65	1.70	0.061	0.065	0.067	
е		0.95 BSC		0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L ₁	0.60 Ref				0.024 Ref		
L ₂		0.25 BSC			0.010 BSC		
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ_1		7° Nom		7° Nom			
ECN: C DWG: 5		ev. I, 18-Dec	c-06				

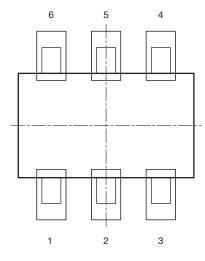
PAD Pattern



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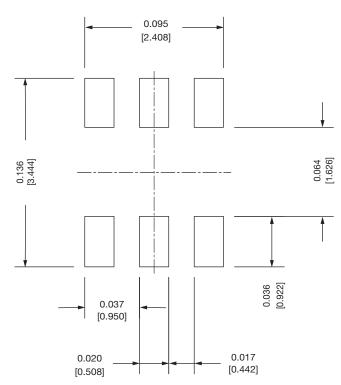
Recommended Land Pattern For TSOP-5L / TSOP-6L











Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev.	B, 24-Oct-2022		
DWG: 3010			

1



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